

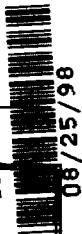
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To the Assistant Commissioner for Patents. Please record the attached original documents or copy thereof.

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<p>1. Name of conveying party(ies):</p> <p>1) Timothy F. Carden 2) Aleksander Zubelewicz</p> <p>Additional names of conveying party(ies) attached? <input type="checkbox"/> yes <input checked="" type="checkbox"/> no</p>		<p>2. Name and address of receiving party(ies):</p> <p>Name: <u>International Business Machines Corporation</u></p> <p>Internal Address:</p> <p>A New York corporation</p> <p>Street Address: <u>New Orchard Road</u> City <u>Armonk</u> State <u>New York</u> Zip <u>10504</u></p> <p>Additional name(s) & address(es) attached? <input type="checkbox"/> yes <input checked="" type="checkbox"/> no</p>	
<p>3. Nature of Conveyance</p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other</p> <p>Execution Date: 1) <u>8/18/98</u>, 2) <u>8/20/98</u></p>			
<p>4. Application number(s) or patent number(s):</p> <p>Title: <u>ASSEMBLY PROCESS FOR FLIP CHIP PACKAGE HAVING A LOW STRESS CHIP AND RESULTING STRUCTURE</u></p> <p>If this document is being filed together with a new application, the execution date of the application is <u>8/18/98</u>, <u>8/20/98</u></p> <p>A. Patent Application No(s). <u>EN997147</u></p> <p>B. Patent No(s). : : :</p> <p>Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>			
<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>William N. Hogg Calfee, Halter & Griswold LLP 1400 McDonald Investment Center 800 Superior Avenue Cleveland, Ohio 44114-2688</p> <p>Certificate of Mailing Under 37 CFR 1.10 I hereby certify that, on the date shown below, this correspondence is being deposited with the United States Postal Service in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231, as "Express Mail Post Office to Addressee" Mailing Label No. <u>EM589153715US</u> on <u>08/25/98</u></p> <p><u>George F. Bruner</u> Name of Person Mailing paper</p> <p><u>8/25/98</u> Date</p>		<p>6. Total number of applications and patents involved: <u>1</u></p> <p>7. Total fee (37 CFR 3.41): <u>\$ 40.00</u></p> <p><input type="checkbox"/> Enclosed</p> <p><input checked="" type="checkbox"/> Authorized to be charged to deposit account <input checked="" type="checkbox"/> Total fee due <input checked="" type="checkbox"/> Any deficiencies in the enclosed fees</p> <p>8. Deposit account number: <u>09-0457</u></p> <p>(Attach duplicate copy of this page if paying by deposit account)</p>	
<p>DO NOT USE THIS SPACE</p>			
<p>9. Statement and signature</p> <p>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</p> <p><u>Lawrence R. Fraley</u> Reg. No. 26,885 Tel: 607-755-3207</p> <p><u>Lawrence R. Fraley</u> <u>Aug. 24, 1998</u> Signature Date</p> <p>Total number of pages comprising this submission: <u>1</u></p>			

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ASSIGNMENT

Whereas, I

Inventor and City and	(1) Timothy F. Carden County of Broome	City of Vestal and State of New York
	(2) Aleksander Zubelewicz County of Broome	City of Binghamton and State of New York

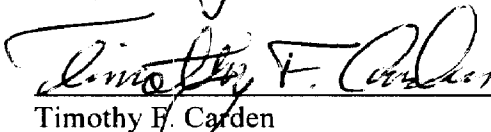
have invented certain improvements in

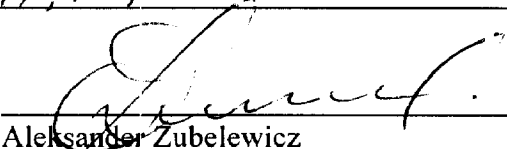
Title ASSEMBLY PROCESS FOR FLIP CHIP PACKAGE HAVING A LOW STRESS CHIP AND RESULTING STRUCTURE

Date That and have executed, respectively, a United States patent application therefor on
Inventor
Signed the (1) 8/20/ 1998, and (2) 8/18/ 1998
Declaration

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patent to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and I request the Commissioner of Patents to issue and Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and I hereby agree that IBM may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

City (1) Signed at Endicott, NY
Date on 8/20/98

Timothy F. Carden Signature
inventor

City (2) Signed at Endicott, NY
Date on Aug 18, 98

Aleksander Zubelewicz Signature
inventor